

07-11-2001

SET

U.S. DEPARTMENT OF COMMERCE  
Patent and Trademark Office



101773872

Tab settings

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):  
**Hirotooshi Tanimura**  
**Keiichi Ohtsubo**  
**Shinji Ueno**

2. Name and address of receiving party(ies):  
Name: **International Business Machines Corporation**

Internal Address:

Street Address: **New Orchard Road**

City: **Armonk** State: **NY** ZIP: **10504**

Additional name(s) & address(es) attached?  Yes  No

Additional names(s) of conveying party(ies)  Yes  No

3. Nature of conveyance:

**MED 6-26-01**

- Assignment  Merger
- Security Agreement  Change of Name
- Other

Execution Date: **6/6/01**

4. Application number(s) or registration numbers(s):

If this document is being filed together with a new application, the execution date of the application is: **6/6/01**

A. Patent Application No.(s)

**09892004**

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **Lawrence R. Fraley**

Internal Address: **IBM Corporation, N50/040-4**

Street Address: **1701 North Street**

City: **Endicott** State: **NY** ZIP: **13760**

6. Total number of applications and patents involved: **1**

7. Total fee (37 CFR 3.41):.....\$ **40.00**

- Enclosed - Any excess or insufficiency should be credited or debited to deposit account
- Authorized to be charged to deposit account

8. Deposit account number:

**09-0457**

07/10/2001 09:58:11 00000164 090437 09892004

DO NOT USE THIS SPACE

09 FC:581 40.00 CH

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

**Lawrence R. Fraley, Reg. No. 26,885**

**June 26, 2001**

Name of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments, and document: **2**

PATENT

**A S S I G N M E N T**

Whereas, we

(1) Hirotoshi Tanimura  
2-23-202 Wakatake-cho, Kusatsu-shi  
Shiga-ken, Japan

(2) Keiichi Ohtsubo  
1368-51 Goudo, Ohmi-chi, Sakata-gun  
Shiga-ken, Japan

(3) Shinji Ueno  
21-60-305 Suehiro-cho, Suita-shi  
Ohsaka-fu, Japan

have invented certain improvements in

ELECTRONIC PACKAGE WITH PLURALITY OF SOLDER-APPLIED AREAS PROVIDING HEAT TRANSFER  
and have executed, respectively, a United States patent application therefor on  
(1) JUN/06/2001, and (2) Jun/06/2001, and (3) Jun/06/2001.

And whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we the above named hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

SIGNED AT:

at Yasu, this 06 day of JUN, 2001.  
Hirotoshi Tanimura  
Hirotoshi Tanimura

at Yasu, this 06 day of Jun, 2001.  
Keiichi Ohtsubo  
Keiichi Ohtsubo

at Yasu, this 06 day of Jun, 2001.  
Shinji Ueno  
Shinji Ueno